

NCE P-Channel Super Trench Power MOSFET

Description

The NCEP30PT16G uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- ●DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

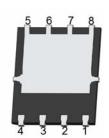
General Features

- V_{DS} =-30V,I_D =-160A
 - $R_{DS(ON)}$ =2.3m Ω (typical) @ V_{GS} =-10V $R_{DS(ON)}$ =3.3m Ω (typical) @ V_{GS} =-4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- · Pb-free lead plating
- 100% UIS tested

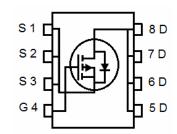
100% UIS TESTED! 100% ΔVds TESTED!

DFN 5X6





Top View Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP30PT16G	NCEP30PT16G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	-160	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	-112	Α
Pulsed Drain Current	I _{DM}	-640	Α
Maximum Power Dissipation	P _D	150	W
Derating factor		1.2	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	1076	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	R _{eJC}	0.83	°C/W

NCEP30PT16G

Electrical Characteristics (T_C=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1.0	-1.5	-2.2	V
Drain Course On State Registeres	-	V _{GS} =-10V, I _D =-80A	-	2.3	2.7	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-80A	-	3.3	4.0	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-80A	-	30	-	S
Dynamic Characteristics (Note4)	<u>.</u>					
Input Capacitance	C _{lss}	V _{DS} =-15V,V _{GS} =0V,	-	7962	-	PF
Output Capacitance	C _{oss}		-	2380	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	216	-	PF
Switching Characteristics (Note 4)	<u>.</u>					
Turn-on Delay Time	t _{d(on)}		-	18	-	nS
Turn-on Rise Time	t _r	V_{DD} =-15V, I_{D} =-80A	-	13	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_G =1.6 Ω	-	90	-	nS
Turn-Off Fall Time	t _f		-	25	-	nS
Total Gate Charge	Qg	V _{DS} =-15V,I _D =-80A,	-	106.5	-	nC
Gate-Source Charge	Q _{gs}		-	15.7		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =-10V	-	16.9		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-80A	-		-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-160	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =-80A	-		35	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-		85	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}\text{=-15V}$,V $_{\text{G}}\text{=-10V}$,L=0.5mH,Rg=25 Ω



Typical Electrical and Thermal Characteristics

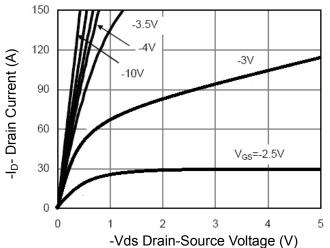


Figure 1 Output Characteristics

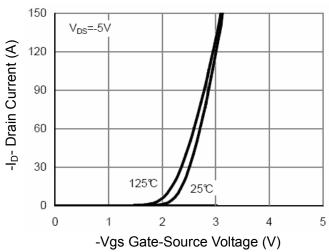
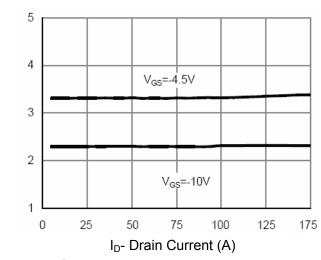


Figure 2 Transfer Characteristics



Rdson On-Resistance(m 2)

Figure 3 Rdson- Drain Current

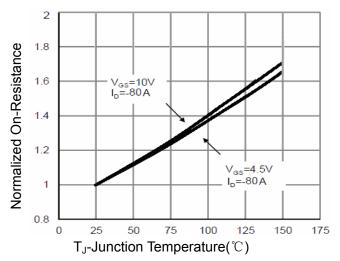


Figure 4 Rdson-JunctionTemperature

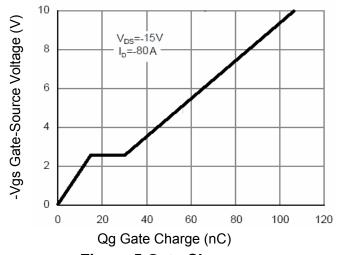


Figure 5 Gate Charge

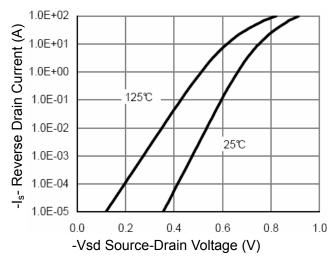


Figure 6 Source- Drain Diode Forward



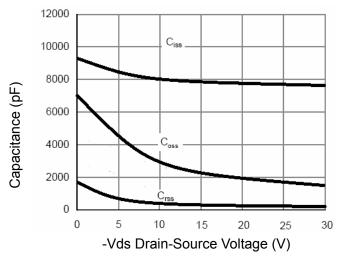


Figure 7 Capacitance vs Vds

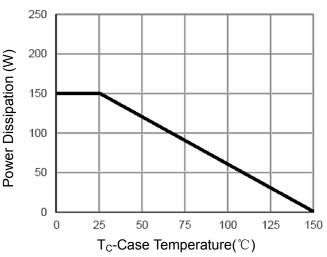


Figure 9 Power De-rating

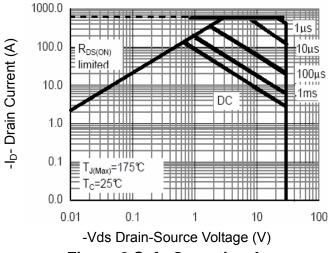


Figure 8 Safe Operation Area

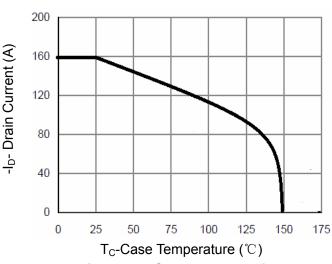


Figure 10 Current De-rating

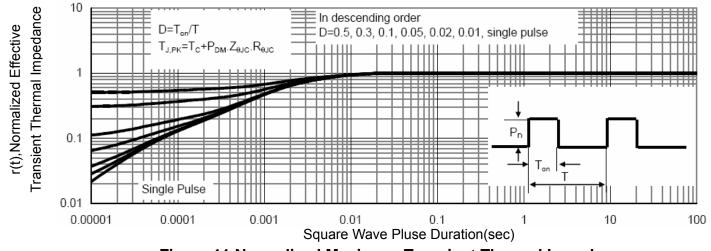
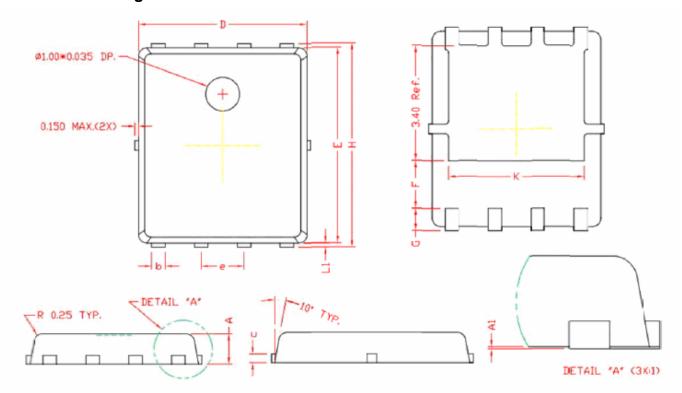


Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	MAX		
A	0.80	0.90	1.00	
A1	0.00	0.03	0.05	
b	0.35	0.42	0.49	
С	0.254 REF.			
D	4.90	5.00	5. 10	
F	1.40 REF.			
E	5.70	5. 80	5. 90	
е	1.27 BSC.			
Н	5. 95	6.08	6. 20	
L1	0.10	0. 14	0.18	
G	0.60 REF.			
K	4.00 REF.			

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NCEP30PT16G

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